254

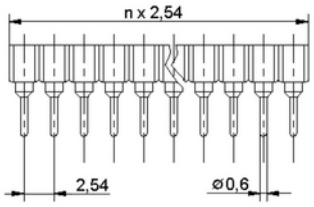
Präzisions-Buchsenleisten - RM 2,54mm - 1-/2-reihig

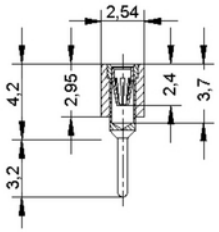
Precision Female Headers - 2,54mm Pitch - Single / Double Row

Technische Daten /*Technical Data*

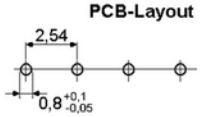
Isolierkörper	Thermoplastischer Kunststoff, nach UL94 V-0
Insulator	*Thermoplastic, rated UL94 V-0*
Kontaktmaterial	Hülse: Messing gedreht
	Feder: 6-Lamellen-Clip, Beryllium-Kupfer
Contact Material	*Sleeve: screw machined brass*
	Clip: 6 Finger-Clip, Beryllium-Copper
Kontaktoberfläche	Lt. Oberflächenoptionen, über Ni (1,3 ... 2,5µm)
Contact Surface	*Acc. to options (see below), over Ni (1,3 ... 2,5µm)*
Lötbarkeit	IEC512-12A
Solderability	*IEC512-12A*
Durchgangswiderstand	< 10mΩ
Contact Resistance	*< 10mΩ*
Isolationswiderstand	$> 10^{10}\Omega$
Insulation Resistance	*$> 10^{10}\Omega$*
Spannungsfestigkeit	$1000V_{RMS}$
Test Voltage	*$1000V_{RMS}$*
Nennstrom	3A
Current Rating	*3A*
Temperaturbereich	-55°C ... +125°C
Temperature Range	*-55°C ... +125°C*
Verarbeitung	Reflow-Lötverfahren; weitere Informationen in Kapitel T
Processing	*Reflow-soldering, detailed information in ch. T*

Single Row - Straight

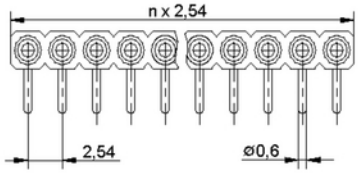


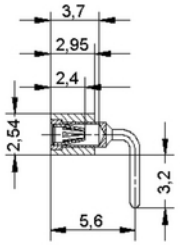


PCB-Layout

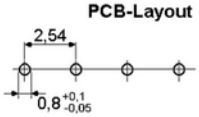


Single Row - Right Angled

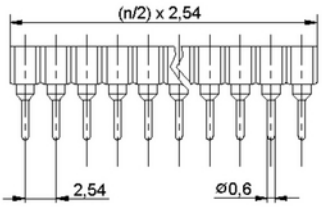


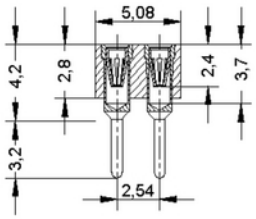


PCB-Layout

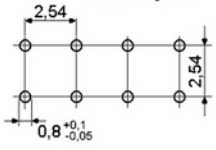


Double Row - Straight





PCB-Layout



Series	***Contacts****	***Type****	***Sleeve Plating***	***Clip Plating****
254	**01**	**2**	**50**	**30**
	01-64 Einreihig *Single row* **04-72** Zweireihig *Double row*	**1** Einreihig, gerade *Single row, straight* **2** Einreihig, gewinkelt *Single row, right angled* **3** Zweireihig, gerade *Double row, straight*	**50** Hülse verzinnt *Tin plated sleeve*	**00** Feder vergoldet *Gold plated clip* **10** Feder 0,25µm Gold *0,25µm gold plated clip* **30** Feder 0,75µm Gold *0,75µm gold plated clip*

(* Bestellbeispiel - Bitte durch Ihre Spezifikationen ersetzen.
** Order example - To be replaced by your specifications.)*

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W+P PRODUCTS

E-MAIL: sales@wppro.com
INTERNET: www.wppro.com

Informationen zum Reflow-Lötverfahren
Reflow-Soldering Information

Reflow-Lötverfahren
Reflow-Soldering

Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflowverfahren verarbeitet werden (Maximalwerte)

Profil Eigenschaft	**Bleifreies Löten**
Durchschnitts-Ramp-Up Rate (Ts_{max} to Tp)	3°C / Sek. Max.
Vorheizen - Temperatur Min (Ts_{min}) - Temperatur Max (Ts_{max}) - Zeit (ts_{min} auf ts_{max})	 150°C 200°C 60-180 Sekunden
Verbleiben oberhalb: - Temperatur (T_L) - Zeit (t_L)	 217°C 60-180 Sekunden
Peak/Klassifizierung Temperatur (Tp)	260°C +/- 5°C
Zeit innerhalb von 5°C um die Peak-Temperatur (tp)	20-40 Sekunden
Ramp-Down Rate	6°C / Sekunde max.
Zeit von 25°C bis zur Peak-Temperatur	8 Minuten max.

Items should be soldered according to IPC/JEDEC J-STD-020C temperature-profile for leadfree reflow-soldering (maximum values):

Profile Feature	**PB-Free assembly**
Average Ramp-Up Rate (Ts_{max} to Tp)	3°C / second max.
Preheat - Temperature Min (Ts_{min}) - Temperature Max (Ts_{max}) - Time (ts_{min} auf ts_{max})	 150°C 200°C 60-180 seconds
Time maintained above: - Temperature (T_L) - Time (t_L)	 217°C 60-180 seconds
Peak/Classification Temperature (Tp)	260°C +/- 5°C
Time within 5°C of actual Peak-Temperature (tp)	20-40 seconds
Ramp-Down Rate	6°C / second max.
Time 25°C to Peak Temperature	8 minutes max.

Empfohlenes Reflow-Lötprofil:
Recommended Reflow-Soldering profile: